



150V 5.7mΩ N-Ch Power MOSFET

Features

- Low $R_{DS(ON)}$
- Low Gate Charge
- 100% UIS Tested, 100% R_g Tested
- Pb-free Lead Plating
- Halogen-free and RoHS-compliant

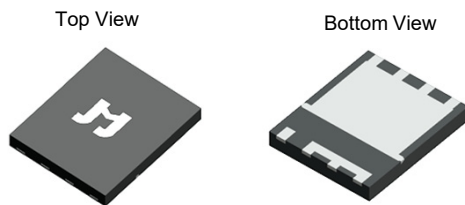
Product Summary

Parameter	Value	Unit
V_{DS}	150	V
$V_{GS(th_Typ)}$	2.1	V
I_D (@ $V_{GS} = 10V$) ⁽¹⁾	105	A
$R_{DS(ON_Typ)}$ (@ $V_{GS} = 10V$)	5.7	mΩ
$R_{DS(ON_Typ)}$ (@ $V_{GS} = 4.5V$)	7.1	mΩ

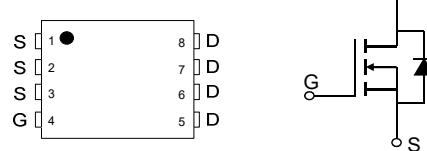
Applications

- Power Management in Telecom., Industrial Automation, CE
- Current Switching in DC/DC & AC/DC (SR) Sub-systems
- Motor Driving in Power Tool, E-vehicle, Robotics

V-DFN5060-8



Pin Configuration
Top View

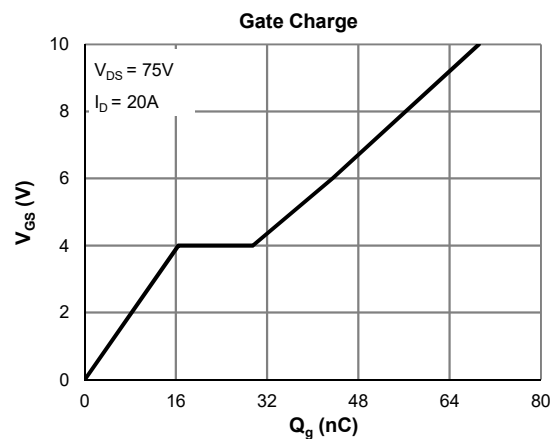
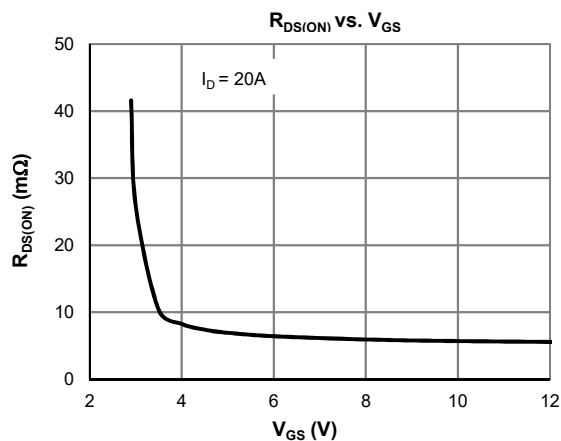


Ordering Information

Device	Package	# of Pins	Marking	MSL	T_J (°C)	Media	Quantity (pcs)
JMSL1507AGN-13	V-DFN5060-8	8	SL1507A	1	-55 to 150	13-inch Reel	5000

Absolute Maximum Ratings (@ $T_A = 25^\circ C$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DS}	150	V
Gate-to-Source Voltage	V_{GS}	±20	V
Continuous Drain Current ⁽¹⁾	I_D	$T_C = 25^\circ C$	105
		$T_C = 100^\circ C$	66
Pulsed Drain Current ⁽²⁾	I_{DM}	420	A
Avalanche Current ⁽³⁾	I_{AS}	44	A
Avalanche Energy ⁽³⁾	E_{AS}	484	mJ
Power Dissipation ⁽⁴⁾	P_D	$T_C = 25^\circ C$	174
		$T_C = 100^\circ C$	69
Junction & Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C



**Electrical Characteristics** (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

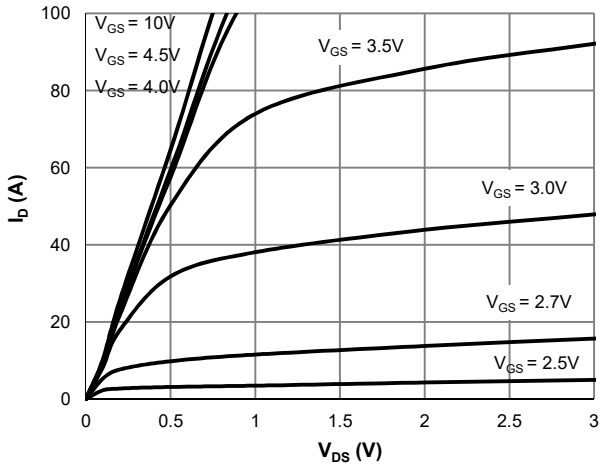
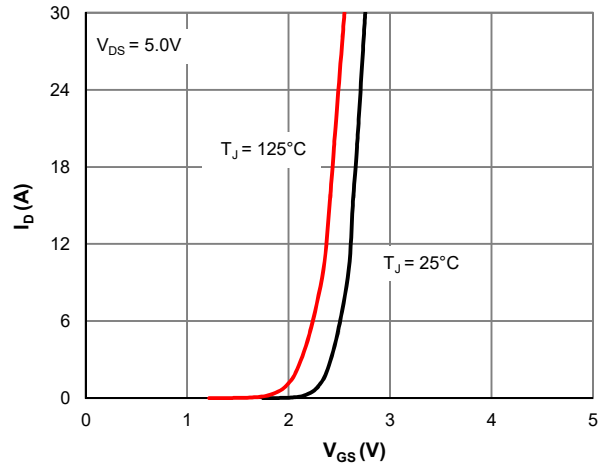
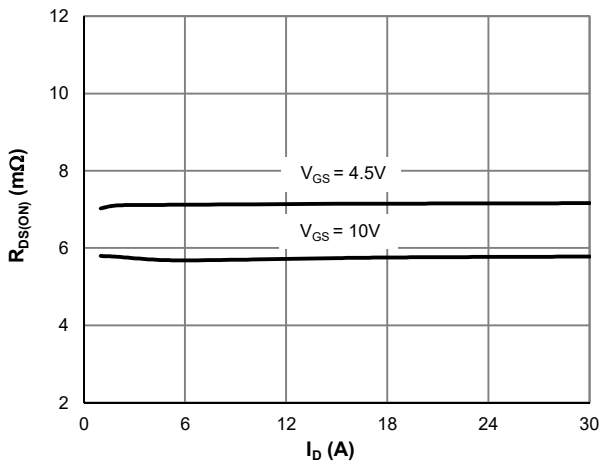
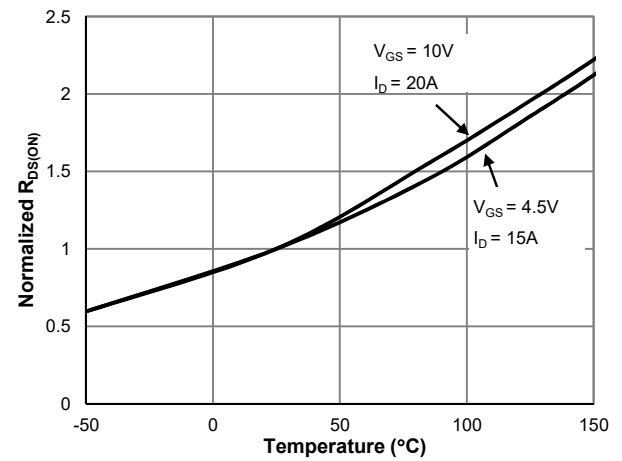
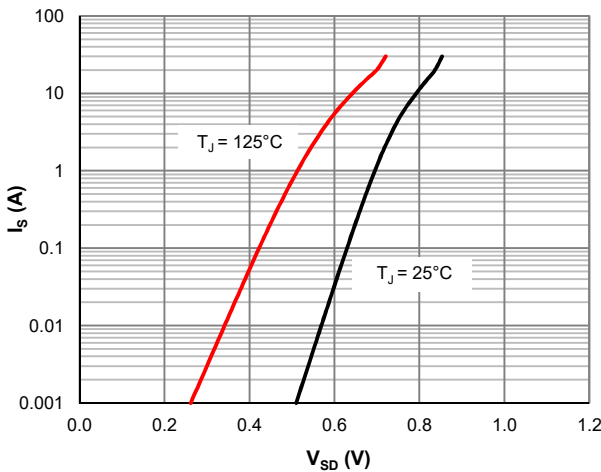
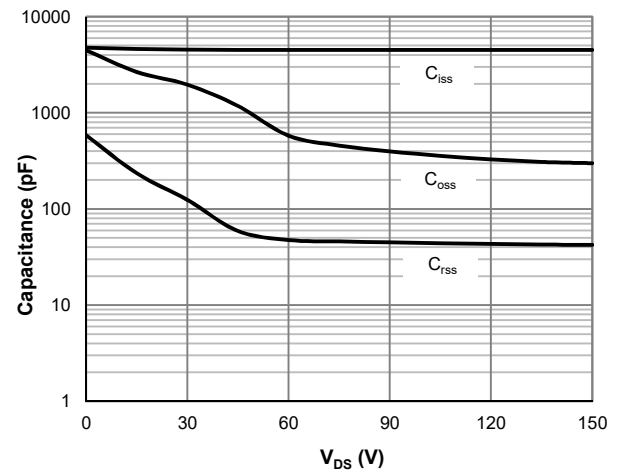
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
STATIC PARAMETERS						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$	150			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 120\text{V}$, $V_{GS} = 0\text{V}$ $T_J = 55^\circ\text{C}$			1.0 5.0	μA
Gate-Body Leakage Current	I_{GSS}	$V_{DS} = 0\text{V}$, $V_{GS} = \pm 20\text{V}$			± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$	1.2	2.1	2.5	V
Static Drain-Source ON-Resistance	$R_{DS(ON)}$	$V_{GS} = 10\text{V}$, $I_D = 20\text{A}$		5.7	7.1	$\text{m}\Omega$
Static Drain-Source ON-Resistance	$R_{DS(ON)}$	$V_{GS} = 4.5\text{V}$, $I_D = 15\text{A}$		7.1	9.2	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{DS} = 5\text{V}$, $I_D = 20\text{A}$		48		S
Diode Forward Voltage	V_{SD}	$I_S = 1\text{A}$, $V_{GS} = 0\text{V}$		0.69	1.0	V
Diode Continuous Current	I_S	$T_C = 25^\circ\text{C}$			174	A
DYNAMIC PARAMETERS ⁽⁵⁾						
Input Capacitance	C_{iss}	$V_{GS} = 0\text{V}$, $V_{DS} = 75\text{V}$, $f = 1\text{MHz}$		4510		pF
Output Capacitance	C_{oss}			457		pF
Reverse Transfer Capacitance	C_{rss}			46		pF
Gate Resistance	R_g	$V_{GS} = 0\text{V}$, $V_{DS} = 0\text{V}$, $f = 1\text{MHz}$		2.2		Ω
SWITCHING PARAMETERS ⁽⁵⁾						
Total Gate Charge (@ $V_{GS} = 10\text{V}$)	Q_g	$V_{GS} = 0$ to 10V $V_{DS} = 75\text{V}$, $I_D = 20\text{A}$		69		nC
Total Gate Charge (@ $V_{GS} = 4.5\text{V}$)	Q_g			34		nC
Gate Source Charge	Q_{gs}			16.5		nC
Gate Drain Charge	Q_{gd}			12.8		nC
Turn-On DelayTime	$t_{D(on)}$	$V_{GS} = 10\text{V}$, $V_{DS} = 75\text{V}$ $R_L = 3.75\Omega$, $R_{GEN} = 6\Omega$		19.5		ns
Turn-On Rise Time	t_r			62		ns
Turn-Off DelayTime	$t_{D(off)}$			86		ns
Turn-Off Fall Time	t_f			105		ns
Body Diode Reverse Recovery Time	t_{rr}		$I_F = 20\text{A}$, $dI_F/dt = 100\text{A}/\mu\text{s}$		96	
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F = 20\text{A}$, $dI_F/dt = 100\text{A}/\mu\text{s}$		273		nC

Thermal Performance

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	50	60	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.42	0.72	$^\circ\text{C}/\text{W}$

Notes:

1. Computed continuous current assumes the condition of T_{J_Max} while the actual continuous current depends on the thermal & electro-mechanical application board design.
2. This single-pulse measurement was taken under $T_{J_Max} = 150^\circ\text{C}$.
3. This single-pulse measurement was taken under the following condition [$L = 500\mu\text{H}$, $V_{GS} = 10\text{V}$, $V_{DS} = 75\text{V}$] while its value is limited by $T_{J_Max} = 150^\circ\text{C}$.
4. The power dissipation P_D is based on $T_{J_Max} = 150^\circ\text{C}$.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Electrical & Thermal Characteristics

Figure 1: Saturation Characteristics

Figure 2: Transfer Characteristics

Figure 3: $R_{DS(ON)}$ vs. Drain Current

Figure 4: $R_{DS(ON)}$ vs. Junction Temperature

Figure 5: Body-Diode Characteristics

Figure 6: Capacitance Characteristics

Typical Electrical & Thermal Characteristics

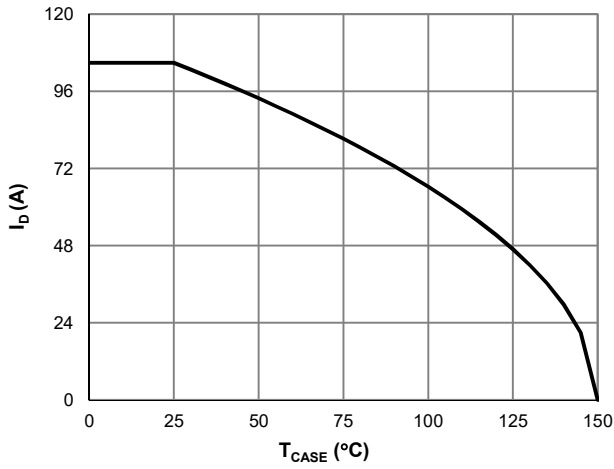


Figure 7: Current De-rating

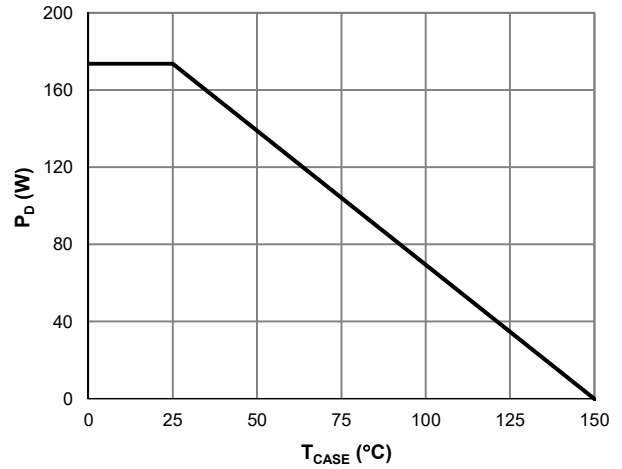


Figure 8: Power De-rating

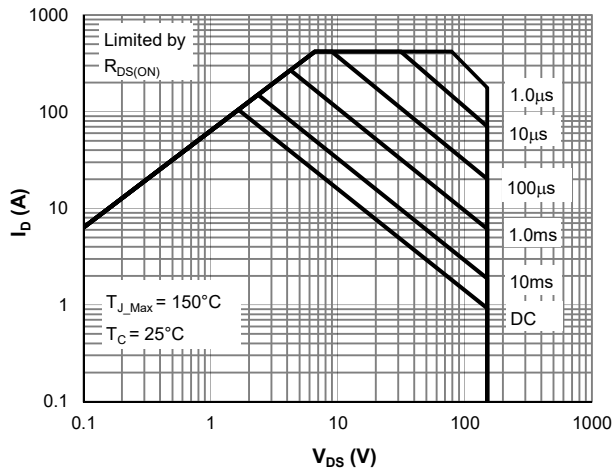


Figure 9: Maximum Safe Operating Area

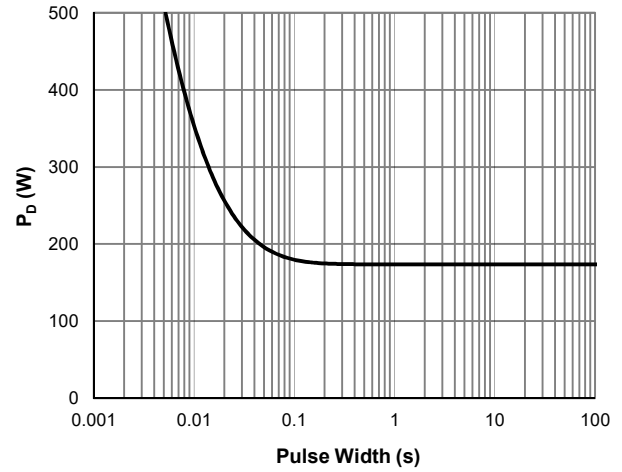


Figure 10: Single Pulse Power Rating, Junction-to-Case

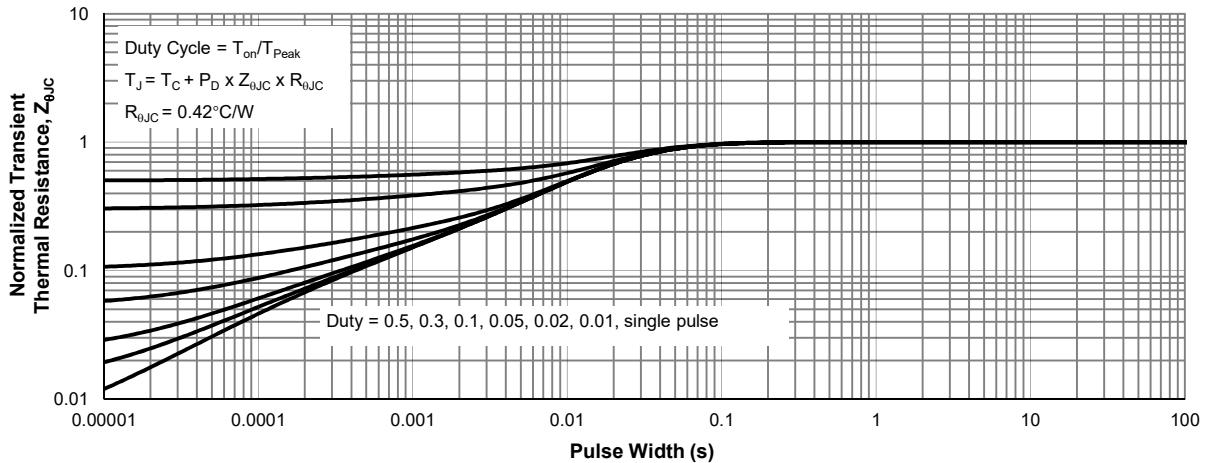
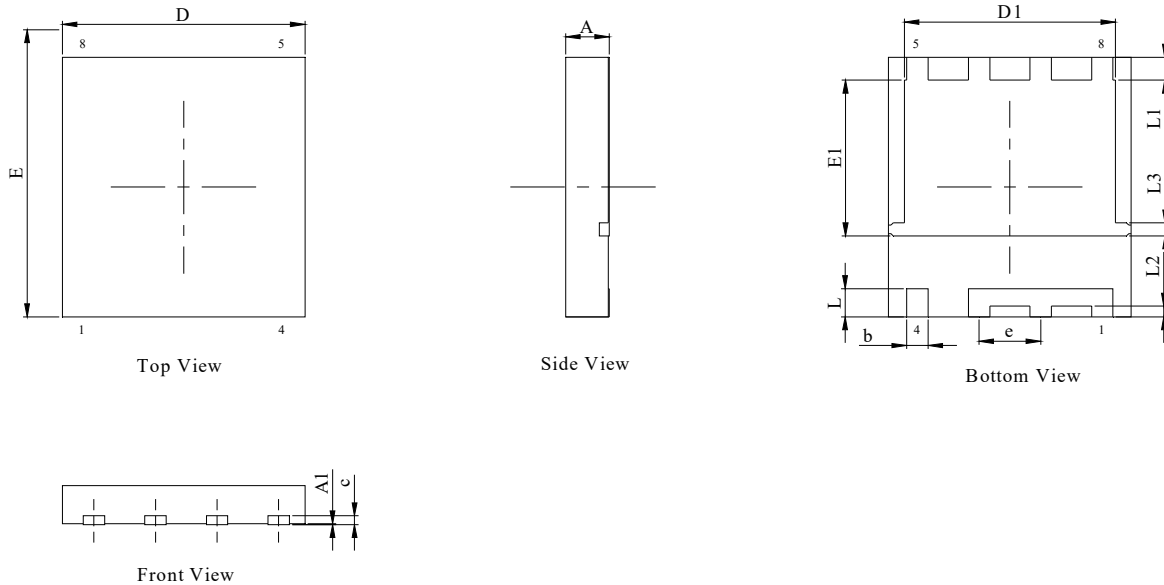


Figure 11: Normalized Maximum Transient Thermal Impedance

V-DFN5060-8 Package Information
Package Outlines


DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	--	--	0.05
b	0.39	0.44	0.49
c	--	0.20	--
D	4.90	5.00	5.10
D1	4.25	4.35	4.45
E	5.90	6.00	6.10
E1	3.47	3.57	3.67
L	0.55	0.65	0.75
L1	0.43	0.53	0.63
L2		0.25	
L3		0.30	
e		1.27 BSC	

Recommended Soldering Footprint
